

SYM	ECN No.	MODIFICATION	DATE	ISSUED

Note:

1.Material:

1.1,Housing: High temperature thermoplastic with/black G/F,UL94v-0

1.2,Contact: copper alloy,t=0.25mm

1.3,Shell: copper/Ferroalloy alloy,t=0.30mm

2.Specification:

2.1,Current rating:1.5A Max.

2.2,Dielectric withstanding

voltage: 100 V(ac) for 1 min.

2.3,Contact resistance: 30 mΩ Max.

2.4,Insulation resistance: 100 MΩ Min.

2.5,Total mating force: 3.57 Kg Max.

2.6,Total unmating force: 1.0 Kg Min.

3.Finish:

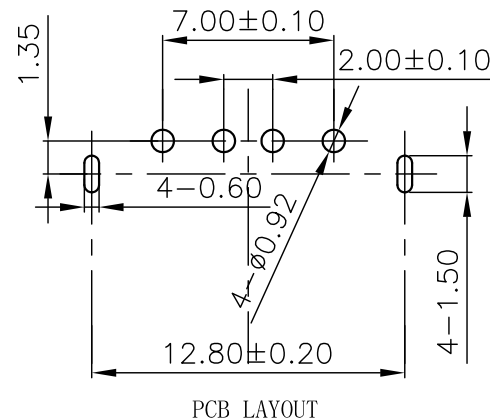
3.1,Contact: Plated Gold in Mating Area:

Tin On Solder Tails

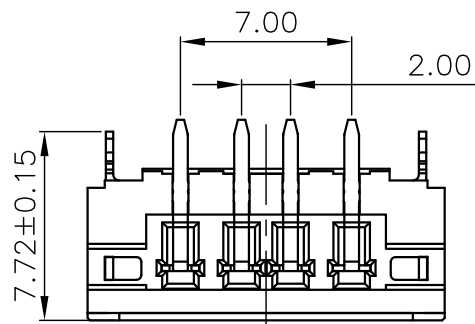
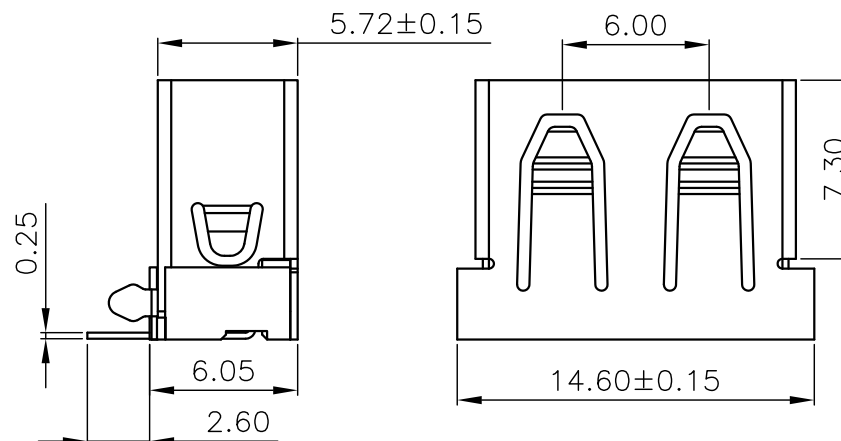
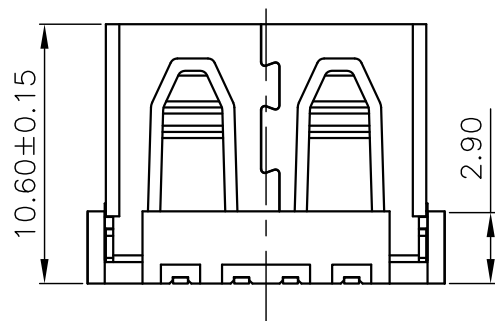
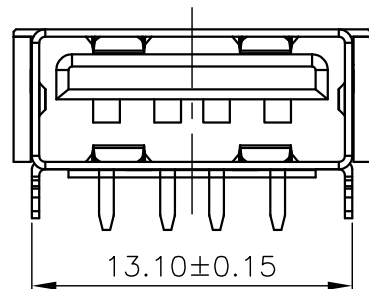
Shell: Nickel Plating

4.Environmental:

4.1,Temperature range: -55°C~85°C



PCB LAYOUT



1	914-821A1011D10201
2	
3	
4	

DRAWN

易芯精密科技(浙江)有限公司
Easychips Precision Technology (Zhejiang) Co., Ltd.

CHECKED

TITLE

AF10.6苹果款后两脚尖弹铁壳

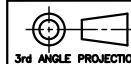
PBT白偏蓝DIP

PART NO.

A914-EC821A1011D10201

APPROVED

DRAWING NO.



3rd ANGLE PROJECTION

UNIT

mm

TOLERANCE

.XXX±.10, .XX±.20, .X±.25, ANG±5°

SCALE

1:1

SHEET

1 OF 1

SIZE

A4

REV.

X1